



产品规格书/Specification

产品/product:	银钯浆料/ Ag/Pd paste
料号/Part number:	02H-1805

适用范围/Application:

此产品适用于厚膜电路、传感器。

Suitable for chip resistor、thick film circuit electrode.

使用条件/Operating conditions:

基材 Substrate	氧化铝陶瓷 Alumina ceramic
印刷 Printing	200-300 目丝网印刷 200-300 mesh stainless screen
流平 Levelling	5-15min minutes at room temperature 室温下流平 5-15 分钟 (时间根据流平的实际情况决定)。
干燥&烧结 Drying & Sintering	通风烘箱烘烤 100-150°C, 10-15 分钟 100-150°C 10-15 min 隧道炉空气气氛下烧结, 峰值 850°C (推荐值), 10 分钟。 Atmospheric firing in belt furnace with peak time of 10 mins at 850°C
Thinner	ST-1000

性能/Characteristics:

1. 浆料性能/Paste Characteristics:

性能 Characteristic	标准 Standard	测试方法及条件 Test method and conditions
1 Fineness	≤5μm	FOG test
2 Viscosity	130-280Pa.s	Brookfield HBT utility cup and spindle (SC4-14/6R), 10rpm, 25±1°C, Brookfield HBT (博利飞) 粘度计, 转子 SC4-14/6R), 10rpm, 25±1°C 粘度可根据用户实际需要调节。

2. 烧结后特性/Characteristics after firing:

在 1 烧结条件下, 膜厚 8-12μm Check fired film produced under the conditions specified in 1), (Film thickness is 8-12μm.)



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特性 Characteristics	Standard 标准	测试方法和条件 Test method and conditions
3 Resistivity 方阻	$\leq 10\text{m}\Omega/\square$	Test pattern 0.6mm×60mm 测试图形 0.6mm×60mm
4 Adhesion strength 附着力		Peel Test: 0.5mm ϕ Tin plated Cu wire soldered on 2mm×2mm Pad. 0.5mm ϕ 锡浸铜线, 焊接面积 2mm×2mm Solder: 96.5Sn/0.5Cu Mildly activated flux used.
Initial 初始附着力	$\geq 46.5\text{N}$	焊料: 96.5Sn/0.5Cu
Ageing 老化附着力	$\geq 26.7\text{N}$	Ageing: 150°C×24hrs 老化条件: 150°C, 24 小时

保存条件, 有效期/Storage condition and Term of validity

产品应在 5-25°C 的环境温度下密封储存, 有效期为产品发货之日起 1 年。

The product shall be guaranteed for 1 year after shipping date, keep tightly under at 5-25°C

包装方式/Packaging method:

标准包装, 1000g/罐, 样品可提供 200 克小罐包装

Standard package 1000g/can, if you need sample to test, available 200g with small package.